

## PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>KUO-YU CHENG</td> <td>01/23/2014</td> </tr> <tr> <td>WEI-KUNG TSAI</td> <td>01/23/2014</td> </tr> <tr> <td>KUAN-CHI TSAI</td> <td>01/24/2014</td> </tr> </tbody> </table>		Name	Execution Date	KUO-YU CHENG	01/23/2014	WEI-KUNG TSAI	01/23/2014	KUAN-CHI TSAI	01/24/2014		
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RECEIVING PARTY DATA											
<table border="1"> <tr> <td>Name:</td> <td>TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.</td> </tr> <tr> <td>Street Address:</td> <td>NO.8, LI-HSIN ROAD. 6, SCIENCE-BASED INDUSTRIAL PARK</td> </tr> <tr> <td>City:</td> <td>HSIN-CHU</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.	Street Address:	NO.8, LI-HSIN ROAD. 6, SCIENCE-BASED INDUSTRIAL PARK	City:	HSIN-CHU	State/Country:	TAIWAN	Postal Code:	300-77
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PROPERTY NUMBERS Total: 1											
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14161208</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14161208						
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Application Number:	14161208										
CORRESPONDENCE DATA											
<p>Fax Number: (703)205-8050</p> <p>Phone: 703-205-8000</p> <p>Email: tuyen.y.ly@bskb.com, mailroom@bskb.com</p> <p><i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i></p> <p>Correspondent Name: BIRCH, STEWART, KOLASCH &amp; BIRCH, LLP</p> <p>Address Line 1: P.O. BOX 747</p> <p>Address Line 4: FALLS CHURCH, VIRGINIA 22040-0747</p>											
ATTORNEY DOCKET NUMBER:	0941-2912PUS1										
NAME OF SUBMITTER:	TUYEN LY										
Signature:	/tuyen ly/										
Date:	02/11/2014										
<p>Total Attachments: 2</p> <p>source=2014-02-12-ASSIGNMENT-0941-2912PUS1-2#page1.tif</p> <p>source=2014-02-12-ASSIGNMENT-0941-2912PUS1-2#page2.tif</p>											

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## ASSIGNMENT

WHEREAS, Kuo-Yu CHENG, Wei-Kung TSAI, and Kuan-Chi TSAI  
hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as  
described and set forth in the below identified application for United States Letters Patent:

Title: SEMICONDUCTOR DEVICE STRUCTURE WITH METAL RING ON  
SILICON-ON-INSULATOR (SOI) SUBSTRATE

Filed: 01/22/2014

Serial No. 14/161,208

Executed on: 01/23/2014; 01/24/2014

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd. of No.8, Li-Hsin Road. 6,  
Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. hereinafter referred to as  
ASSIGNEES, is desirous of acquiring ASSIGNOR'S interest in the said invention and application  
and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and  
valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have  
sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said  
Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to  
the said invention and application and all future improvements thereon, and in and to any Letters  
Patent which may hereafter be granted on the same in the United States, the said interest to be held  
and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by  
said Assignor had this Assignment and transfer not been made, to the full end and term of any  
Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or  
in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee,  
but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or  
applications, execute, verify, acknowledge and deliver all such further papers, including  
applications for Letters Patent and for the reissue thereof, and instruments of assignment and  
transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or  
maintain Letters Patent for said invention and improvement, and to vest title thereto in said  
Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s)  
indicated.

kychenge 2014/01/23 11:14:28

# ASSIGNMENT

2014/1/23      Kuo-Yu Cheng  
Date      Name: Kuo-Yu CHENG      (Last name: CHENG)

2014/1/23      Wei-Kung Tsai  
Date      Name: Wei-Kung TSAI      (Last name: TSAI)

2014/1/24      Kuan-Chi Tsai  
Date      Name: Kuan-Chi TSAI      (Last name: TSAI)